



<b>ENVIRONMENTAL AND PACKAGE TESTING DATA FOR ChipFET® (1206-8)</b>					
<b>STRESS</b>	<b>SAMPLE SIZE</b>	<b>DEVICE HR./CYC</b>	<b>CONDITION</b>	<b>TOTAL FAILS</b>	<b>FAIL PERCENTAGE</b>
HAST	250	25 000	130 °C, 85 % RH	0	0
Pressure Pot	500	48 000	121°, 15 PSIG	0	0
Solder DUNK	10	30	260 °C, 10 s	0	0
Temp. Cycle	1282	611 000	-55 °C to 150 °C	0	0